



**TOREX Semiconductor Ltd.**  
Sakura Ninonbashi Bldg. 8F  
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Japan  
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<http://www.torex.co.jp>

Apr. 23rd, 2008

**Dear Customer,**

**Re: Environmental Declaration for TOREX's products**

We hereby declare that our products produced under our environmental management system certified by **ISO14001 (Certificate No. JQA-EMS3035)**. We are also implementing green procurement based primarily on the requirements of **SONY's Green Partner (Certificate No.SSR6432)**, and any substances banned under its standard SS-00259 including six substances referred under **EU RoHS Directive 2002/95/EC** and **ACPEIP: 电子信息产品污染控制管理办法 (2006)** listed below are not intentionally used in the products (except for exempted applications by the directive); otherwise, the content levels of such substances as impurity do not exceed the limits specified by these standards.

- ◇ Cadmium
- ◇ Lead
- ◇ Mercury
- ◇ Chromium VI
- ◇ PBB
- ◇ PBDE

If any circumstances occurred due to a violation against the non-use statement above, we will sincerely reach a negotiated settlement with our customers, who have a direct contract with TOREX Semiconductor Ltd., for the damage.

\*Attached are the composition table and measurement results data.

Takara Yoshida  
General Manager, Quality Assurance Dept.

To: YIFANG DIGITAL (HONG KONG) COMPANY LIMITED

2008/4/23

TOREX Semiconductor Device HK Ltd.(BSE)  
TOREX Semiconductor Ltd.

## Composition Table

Product(Pb-free): XC62FPXXXXPR

Typical Mass: 51 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
IC chip	0.705	Silicon	13800	7440-21-3
Leadframe	20.083	Copper	393800	7440-50-8
	0.060	Tin	1200	7440-31-5
	0.050	Zinc	1000	7440-66-6
	0.067	Chromium	1300	7440-47-3
	0.802	Silver	15700	7440-22-4
Die attach adhesive	0.032	Epoxy	600	-
	0.126	Silver	2500	7440-22-4
Bonding wire	0.030	Gold	600	7440-57-5
Molding compound	22.822	Silica	447500	60676-86-0
	3.501	Epoxy resin	68600	-
	1.144	Phenol resin	22400	-
	0.512	Antimony trioxide	10000	1309-64-4
	0.492	Brominated resin	9700	-
	0.174	Organic phosphorus	3400	-
Plating (1)	0.008	Bismuth	200	7440-69-9
	0.392	Tin	7700	7440-31-5
Plating (2)	0.400	Tin	7800	7440-31-5

\*The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\*Any indication "-" in CAS number means "confidential."

\*If more than one termination plating types are listed, the composition is either (1), (2), or (3).



# Test Report

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TOREX SEMICONDUCTOR LTD.  
SAKURANIHONBASHI BLDG. 8F, 1-13-12, NIHONBASHI KAYABACHO,  
CHUO-KU, TOKYO 103-0025, JAPAN



The following sample(s) was/were submitted and identified by/on behalf of the client as :


Sample Description : IC  
Style/Item No. : SOT-89  
Sample Receiving Date : 2008/01/29  
Testing Period : 2008/01/29 TO 2008/02/05

Test Requested : In accordance with the RoHS Directive 2002/95/EC, and its amendment directives.

Test Method : With reference to IEC 62321, Ed.1 111/54/CDV  
Procedures for the Determination of Levels of Regulated  
Substances in Electrotechnical Products.

- (1) Determination of Cadmium by ICP-AES.
- (2) Determination of Lead by ICP-AES.
- (3) Determination of Mercury by ICP-AES.
- (4) Determination of Hexavalent Chromium for non-metallic samples by UV/Vis Spectrometry.
- (5) Determination of PBB and PBDE by GC/MS.

Test Result(s) : Please refer to next page(s).

  
Chenyu Kung / Operation Manager  
Signed for and on behalf of  
SGS TAIWAN LTD.  
Chemical Laboratory – Taipei

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TW 6225800



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SAKURANIHONBASHI BLDG. 8F, 1-13-12, NIHONBASHI KAYABACHO,  
CHUO-KU, TOKYO 103-0025, JAPAN

Test results by chemical method (Unit: mg/kg)

Test Item (s):	Method (Refer to)	Result	MDL
		No.1	
Cadmium (Cd)	(1)	n.d.	2
Lead (Pb)	(2)	n.d.	2
Mercury (Hg)	(3)	n.d.	2
Hexavalent Chromium Cr(VI) by alkaline extraction	(4)	n.d.	2
<b>Sum of PBBs</b>		n.d.	-
Monobromobiphenyl		n.d.	5
Dibromobiphenyl		n.d.	5
Tribromobiphenyl		n.d.	5
Tetrabromobiphenyl		n.d.	5
Pentabromobiphenyl		n.d.	5
Hexabromobiphenyl		n.d.	5
Heptabromobiphenyl		n.d.	5
Octabromobiphenyl		n.d.	5
Nonabromobiphenyl		n.d.	5
Decabromobiphenyl		n.d.	5
<b>Sum of PBDEs (Mono to Nona) (Note 4)</b>	(5)	n.d.	-
Monobromobiphenyl ether		n.d.	5
Dibromobiphenyl ether		n.d.	5
Tribromobiphenyl ether		n.d.	5
Tetrabromobiphenyl ether		n.d.	5
Pentabromobiphenyl ether		n.d.	5
Hexabromobiphenyl ether		n.d.	5
Heptabromobiphenyl ether		n.d.	5
Octabromobiphenyl ether		n.d.	5
Nonabromobiphenyl ether		n.d.	5
Decabromobiphenyl ether		n.d.	5
<b>Sum of PBDEs (Mono to Deca)</b>		n.d.	-

## TEST PART DESCRIPTION:

NO.1 : MIXED ALL PARTS

- Note : 1. mg/kg = ppm  
2. n.d. = Not Detected  
3. MDL = Method Detection Limit  
4. According to 2005/717/EC DecaBDE is exempt.  
5. "-" = Not Regulated  
6. The sample(s) was/were analyzed on behalf of the applicant as mixing sample in one testing.  
The above result(s) was/were only given as the informality value.

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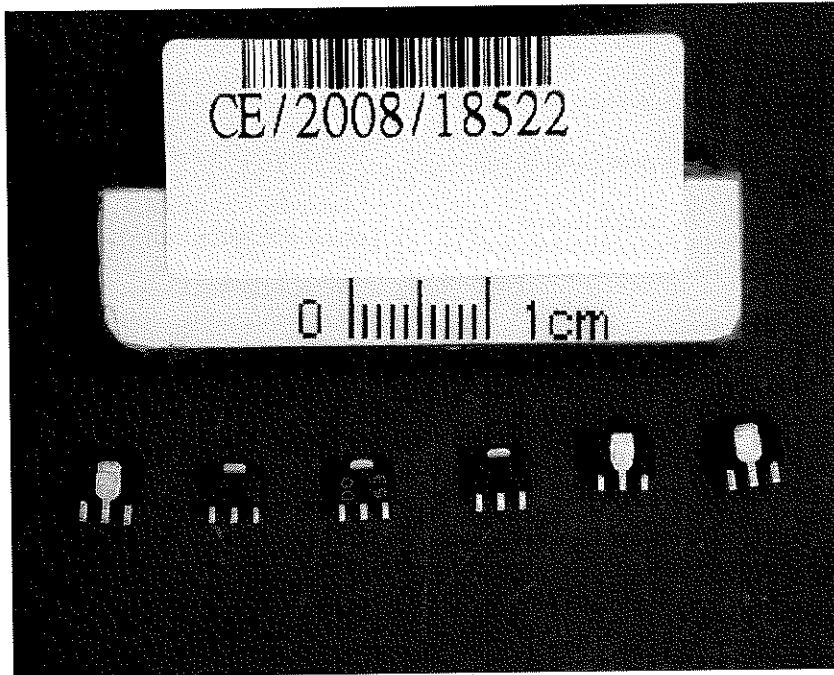


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\*\* End of Report \*\*

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